





SGP.18c

Specification

Part No.	SGP.1575.18.4.C.02
Product Name	GPS SMT Patch Antenna
Features	18mm*18mm*4.5mm 1575MHz Centre Frequency Patent Pending RoHS Compliant



1. Introduction

This ceramic GPS patch antenna is based on smart **XtremeGain™** technology. It is mounted via SMT process and has been selected as optimal solution for the 45x45mm ground plane.

2. Specification

Original Patch Specification tested on 45mm ground plane

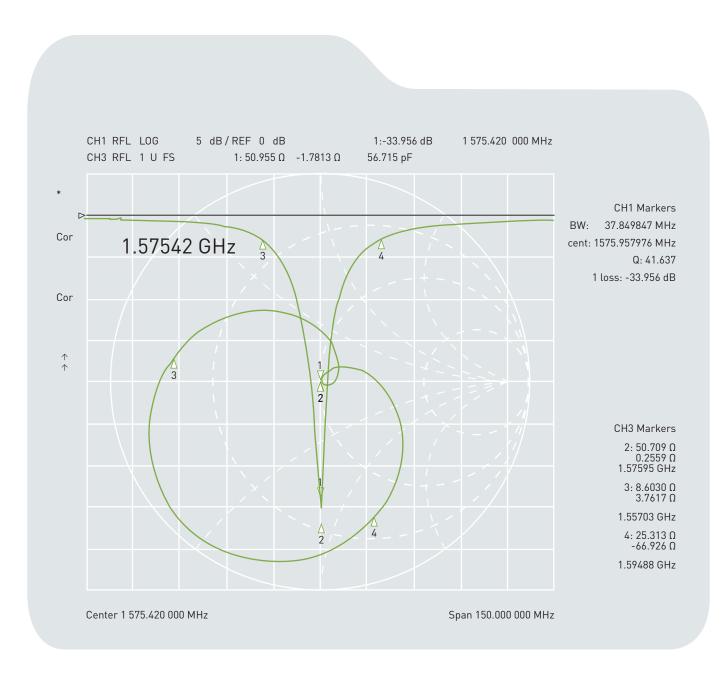
Parameter	Specification	Notes	
Range of Receiving Frequency	1575.42 ± 1.023MHz		
Center Frequency	1575.42 ± 3MHz	With 45*45mm ground plane	
Bandwidth	5MHz min		
Return Loss	≤-10 dB		
VSWR	1.5 max		
Gain at Zenith	+1.0 dBic typ.		
Gain at 10°elevation	-3.0 dBic typ.		
Axial Ratio	4.0 dB max		
Polarization	RHCP		
Impedance	50 Ohms		
Frequency Temperature Coefficient (Tf)	0 ± 20ppm / °C	-40°C to +85°C	
Operating Temperature	-40°C to +85°C		

**Changes in user groundplane and environment will offset centre frequency



3. Electrical Specifications

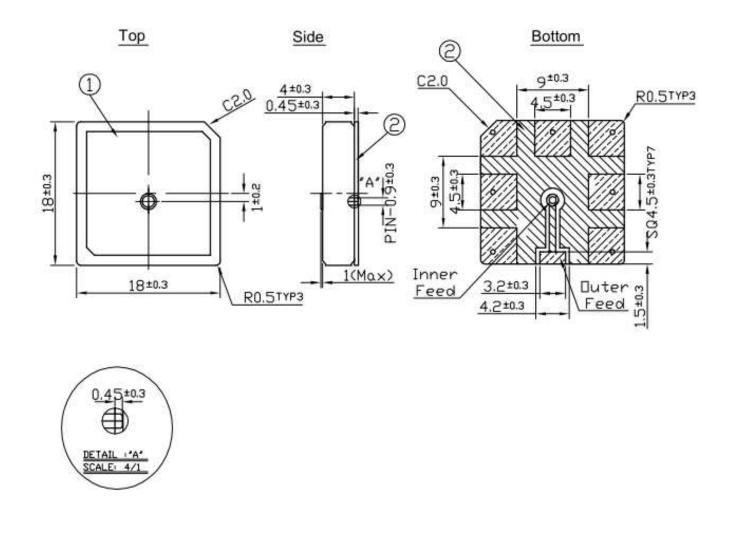
3.1 Return Loss, SWR, Impedance, measured on the test fixture





4. Mechanical Specifications

4.1 Antenna Dimensions and Drawing



NOTE:

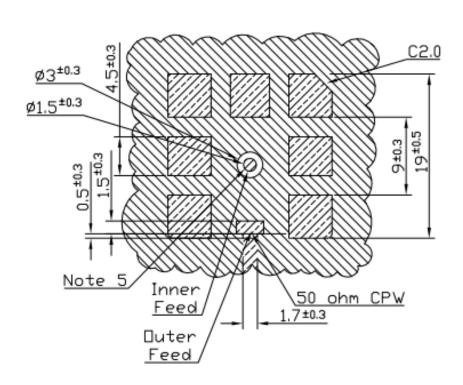
- 1. Solder mask.
- Area to be soldered.
 Dimension of 50 Ohm CPW dependent on individual board.
- 4. Matching circuit-capacitor and inductor values dependent on individual environment
- 5. Must be soldered to complete antenna feed connection

	Name	Part No.	Material	Finish	Quantity	
1	SGP.18 Patch 18x18x4	SGP.18c	Ceramic	Clear	1	
2	SGP.18 PCB		FR 0.5t	Green	1	

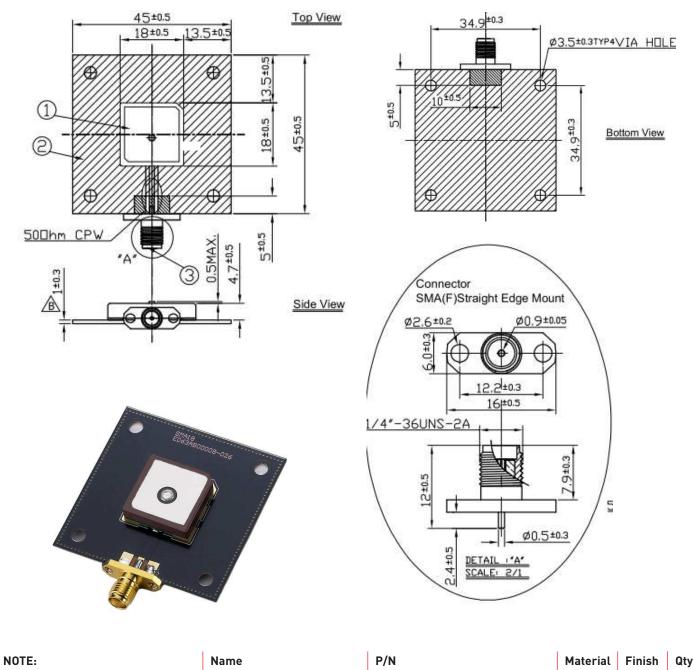


4.2 Antenna footprint (view from underneath)

PCB Footprint







SGP.18c

4.3 Test Jig and Dimension

1. Solder Mask (Black) 2. Solder Area

1

SMA(F)Straight Edge Mount З

SGP.18 Patch 18x18x4

SMA.F.ST.JACK.PANELM.2H.CM	Brass	Gold	1

Ceramic

FR4 1t

Clear

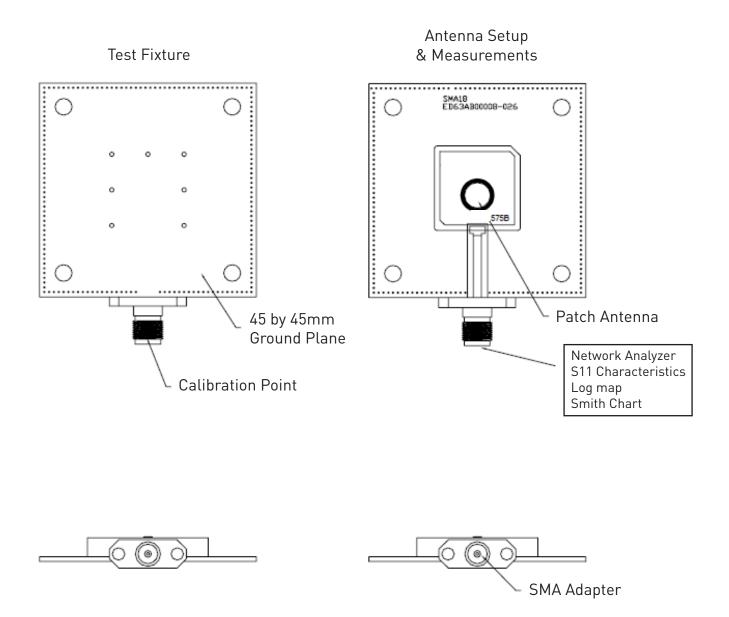
Black

1

1



4.4 Test Fixture set up and measurements





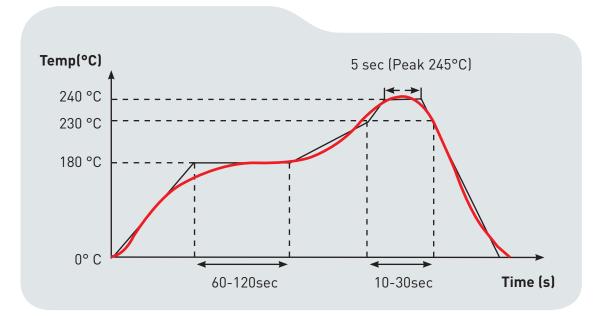
5. Antenna Recommended Soldering Conditions

5.1 Flux, Solder

- Use rosin-based flux. Don't use highly acidic flux with halide content exceeding 0.2wt%(chlorine conversion value).
- Use Sn solder.

5.2 Reflow Soldering Conditions

Pre-heating should be in such a way that the temperature difference between solder and product surface is limited to 150°C max.
 Cooling into solvent after soldering also should be in such a way that temperature difference is limited to 100°C max.
 Unwrought pre-heating may cause cracks on the product, resulting in the deterioration of products quality.



5.3 Reworking with Soldering Iron

• The following conditions must be strictly followed when using a soldering iron.

Pre-heating	150°, 1 min
Tip temperature	290° max
Soldering iron output	30w max
Soldering time	3 second max



5. Packaging

200 pcs / reel / inner carton

5 reels in an outer carton (1000)

